



Selected Papers from ICAM2016 and ICI2016

Guest Editor:

Prof. Dr. Chien-Hung Liu

Department of Mechanical
Engineering, National Chung
Hsing University, 250 Kuo Kuang
Rd., Taichung 402, Taiwan

Deadline for manuscript
submissions:

closed (31 August 2017)

Message from the Guest Editor

Dear Colleagues,

This Special Issue will select the papers related to invention/innovation advanced manufacturing, especially smart manufacturing, from ICI2016 (2016 2nd International Conference on Inventions, <http://sciforum.net/conference/ICI2016>) and ICAM 2016 (2016 International Conference on Advanced Manufacturing, <http://sciforum.net/conference/ICAM2016>).

Smart manufacturing focuses on new and emerging technologies for industry 4.0. Papers with innovative ideas or research results in all aspects of advanced manufacture are also encouraged.

Prof. Dr. Chien-Hung Liu

Guest Editor





an Open Access Journal by MDPI

Editors-in-Chief

Prof. Dr. Chien-Hung Liu

Department of Mechanical
Engineering, National Chung
Hsing University, 250 Kuo Kuang
Rd., Taichung 402, Taiwan

Prof. Dr. Shoou-Jinn Chang

Department of Electrical
Engineering, National Cheng
Kung University, Tainan 701,
Taiwan

Message from the Editorial Board

The unique journal *Inventions* is different from all other journals. Many scholars spend their lives publishing research papers in many different journals, but most of these journals do not help scholars collate and analyze their results or assist in promoting them to a relevant industry. However, *Inventions* will help authors not only to publish their papers in the journal, but also to promote their research results to industry and assist them in realizing the purpose of technology transfer. In the future, *Inventions* will help authors to evaluate their technology license fees based on the valuation theory and approaches and also help authors to show their patents and technologies on a network transaction platform.

Author Benefits

Open Access: free for readers, with article processing charges (APC) paid by authors or their institutions.

High Visibility: indexed within Scopus, ESCI (Web of Science), Inspec, Ei Compendex and other databases.

Journal Rank: JCR - Q2 (*Engineering, Multidisciplinary*) / CiteScore - Q1 (General Engineering)

Contact Us

Inventions Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland

Tel: +41 61 683 77 34
www.mdpi.com

mdpi.com/journal/inventions
inventions@mdpi.com